

(19) World Intellectual Property
Organization
International Bureau



(10) International Publication Number

WO 2022/245576 A9

(43) International Publication Date
24 November 2022 (24.11.2022)

WIPO | PCT

(51) International Patent Classification:

H05K 3/42 (2006.01) C25D 5/18 (2006.01)
C25D 3/38 (2006.01) H05K 1/02 (2006.01)
C25D 5/00 (2006.01) H05K 1/18 (2006.01)

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(21) International Application Number:

PCT/US2022/028462

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(22) International Filing Date:

10 May 2022 (10.05.2022)

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN,
HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH,
KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA,
MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,
NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU,
RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM,
ZW.

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/189,640 17 May 2021 (17.05.2021) US

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(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ,
TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU,
TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE,

(54) Title: SINGLE STEP ELECTROLYTIC METHOD OF FILLING THROUGH HOLES IN PRINTED CIRCUIT BOARDS AND OTHER SUBSTRATES

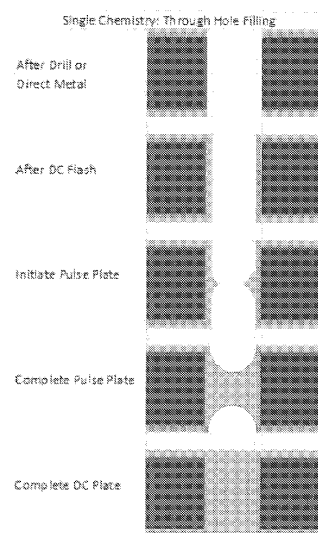


Figure 1

(57) Abstract: A method of copper electroplating in the manufacture of printed circuit boards. The method is used for filling through-holes and micro-vias with copper. The method includes the steps of: (1) preparing an electronic substrate to receive copper electroplating thereon; (2) forming at least one of one or more through-holes and/or one or more micro-vias in the electronic substrate; and (3) electroplating copper in the at least one or more through-holes and/or one or more blind micro-vias by contacting the electronic substrate with an acid copper electrolyte. The acid copper electrolyte is used to plate the one or more through-holes and/or the one or more blind micro-vias. A first pulse reverse plating waveform sequence is used to create a copper bridge in the center of the through-holes followed by direct plating until metallization is complete.

DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU,
LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK,
SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *of inventorship (Rule 4.17(iv))*

Published:

— *with international search report (Art. 21(3))*

(48) Date of publication of this corrected version:

12 October 2023 (12.10.2023)

(15) Information about Correction:

see Notice of 12 October 2023 (12.10.2023)